

## **Master of Entrepreneurship in Technology and Innovation - 01**

**Session :** Electronic Rapid Prototyping

**Assignment N° 01:**

Case study :

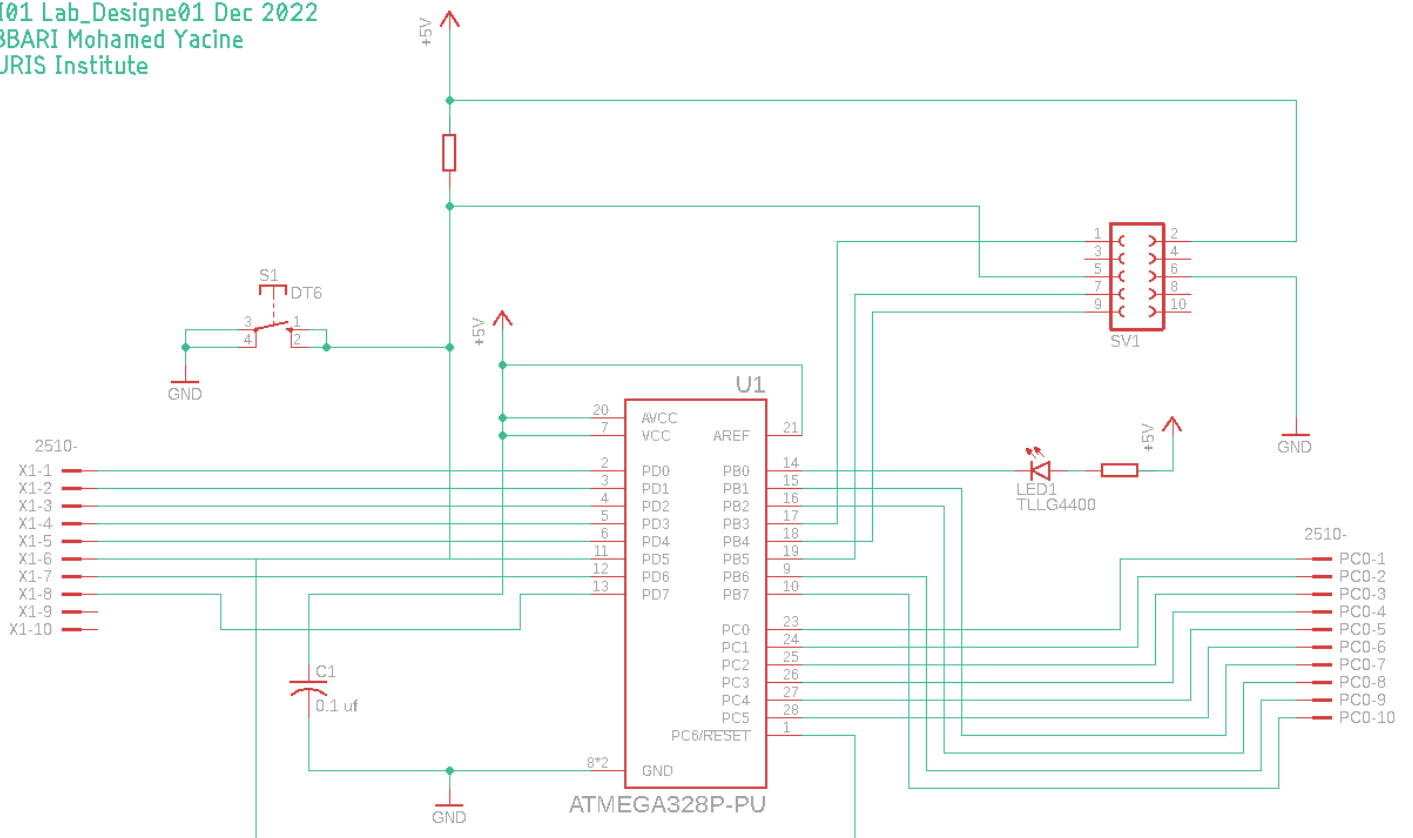
**Lab Design**

*Presented by :*

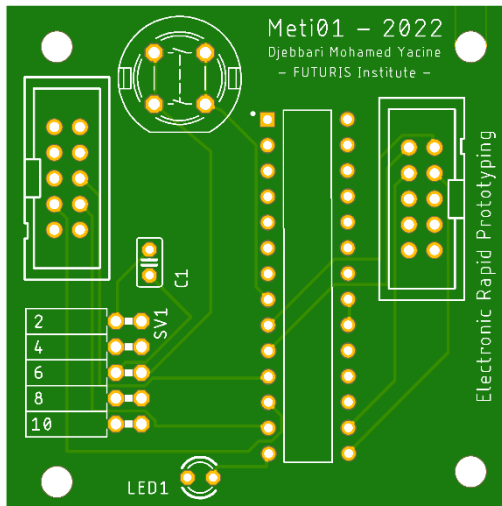
- Mr Mohammed Yacine DJEBBARI

## Schematics :

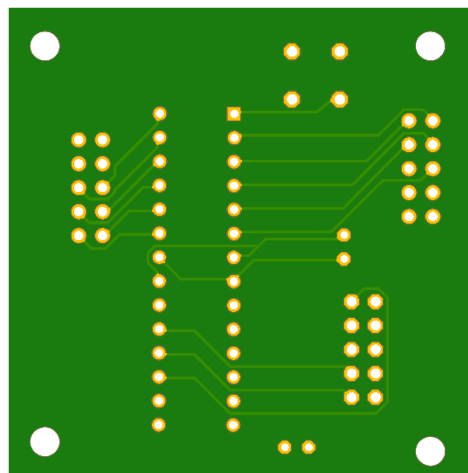
METI01 Lab\_Designe01 Dec 2022  
DJEbbARI Mohamed Yacine  
FUTURIS Institute



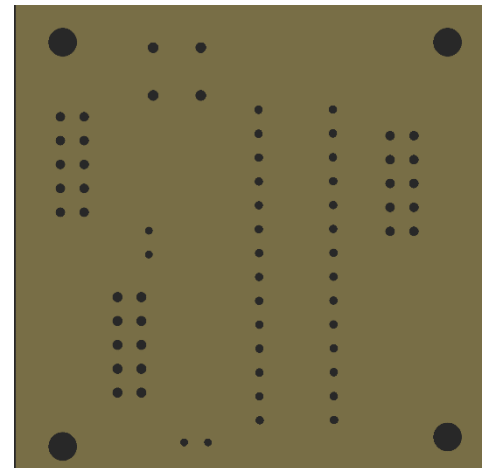
## PCB :



Top Layer Side

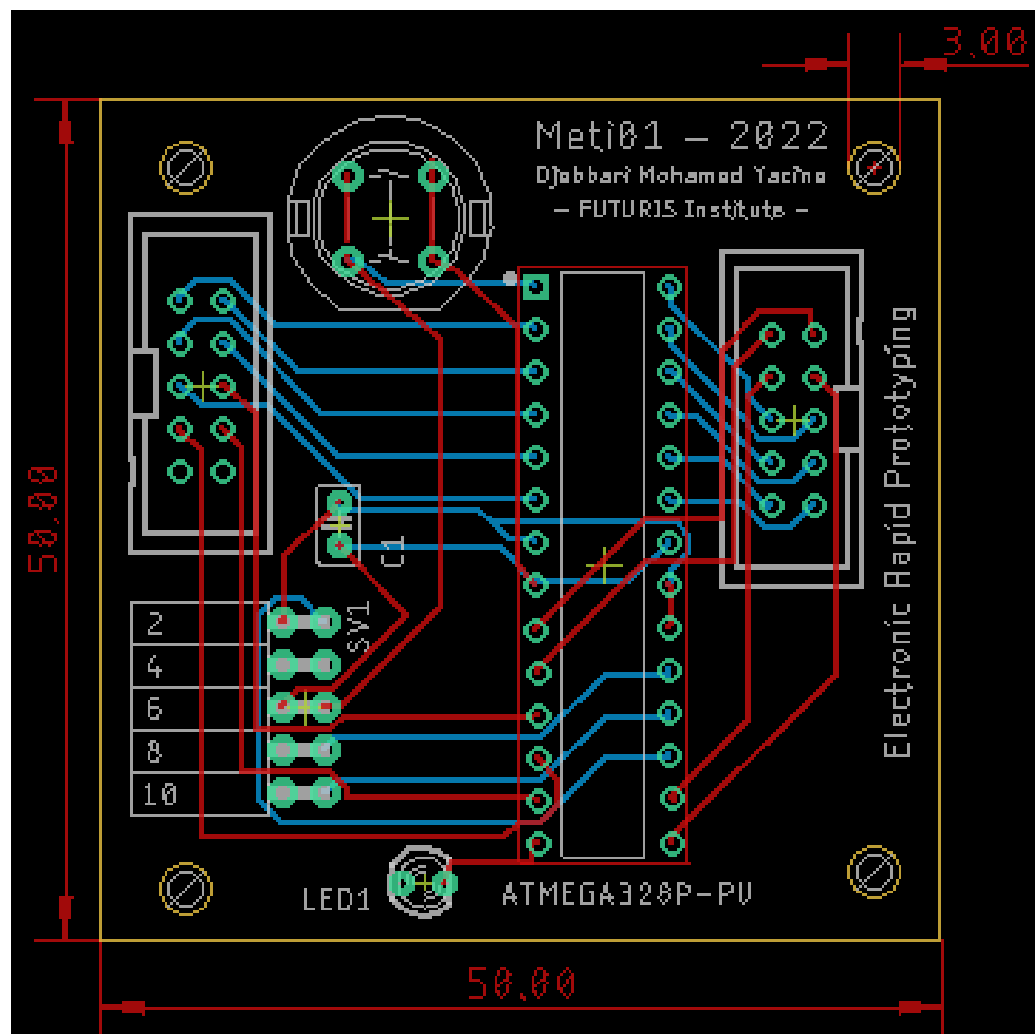


Bottom Layer Side



Drills Layer Side

**Board :**



**BOM file:**

Qty	Value	Device	Package	Parts	Description
1		FE05-2W	FE05-2W	SV1	FEMALE HEADER
1	0.1 uf	C-US025-025X050	C025-025X050	C1	CAPACITOR, American symbol
2	2510-	2510-	PAK100/2500-10	PC0, X1	3M (TM) Pak 100 4-Wall Header
1	ATMEGA328P-PU	ATMEGA328P-PU	DIP794W46P254L2967H457Q28B	U1	ATmega Series 20 MHz 32 KB Flash 2 KB SRAM 8-Bit Microcontroller - DIP-28 Check availability
1	DT6	DT6	DT6	S1	ITT SWITCH
1	TLLG4400	TLLG4400	LED3MM	LED1	Low Current (2mA) LED 3 mm Tinted Diffused Package color GREEN